



## DISCRIPTION

### FEATURES

Ferrite  
High frequency design  
Excellent Q values  
Excellent SRF  
High reliability  
Excellent thermal stability

### OPTIONS

Tape & Reel is Standard ( Qty: 3.000 Pcs )  
Bulk Packing Available for smaller quantites  
Tolerance: J = 5% and K=10% is Standard,  
tighter Tolerance available ( MOQ on request )

### APPLICATIONS

Modems  
Mobile Radios  
Cordless Telephones  
Global Positioning Systems  
Telecommunications Systems

## PHYSICAL CHARACTERISTICS

- Testing : ( Equivalents acceptable ) Inductance & Q-HP4191A + HP4291A  
SRF : HP8553B ; RDC : 25°C
- Operating Temperature : -55°C ~ 85°C
- Pad metalization : Silver-nickel with 90/10 solder
- Solder methods : Wave, Reflow, Vapor Phase
- Solderability : Max 260°C for 10 seconds
- Marking : EIA color code

## ELECTRICAL SPECIFICATIONS

| Properties         | Test conditions |          | Value | Unit | Tol.       |
|--------------------|-----------------|----------|-------|------|------------|
| Inductance         |                 | L        | 68    | µH   | see Site 2 |
| Q factor           |                 | Q        | 25    |      | min.       |
| DC-resistance      |                 | DCR typ. | ---   | Ω    | typ.       |
| DC-resistance      |                 | DCR max. | 4,7   | Ω    | max.       |
| Self-Res. Freq.    |                 | SRF      | 15    | Mhz  | min.       |
| Test-Freq.         |                 |          | 2,52  | Mhz  |            |
| Rated Current      |                 | IDC      | 110   | mA   | max.       |
| Saturation Current |                 | Isat     | ---   | mA   | typ.       |

1. This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon -Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability functions.

### SMT WIRE-WOUND CHIP INDUCTORS

Part No.: **S12008-680**

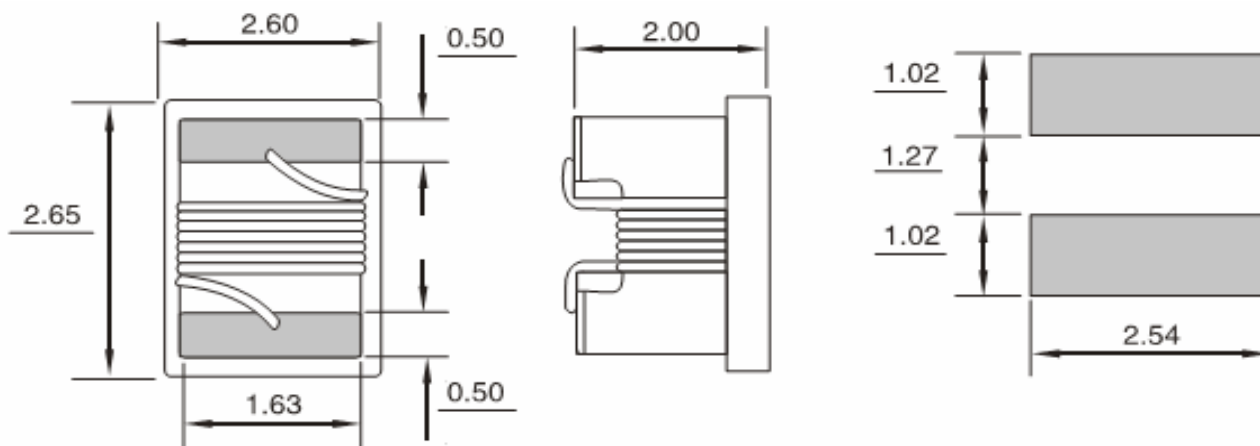
Customer:

|       |       |      |       |        |         |       |            |
|-------|-------|------|-------|--------|---------|-------|------------|
| DRW:  | Chang | CHKD | Young | MATL:  | Chu Chi | DATE  | 09.06.2009 |
| APPD: | Pong  |      |       | FINISH | Vienna  | Sheet | 1 from 2   |



## TECHNICAL INFORMATION

### Dimensions ( mm )



### Ordering Information

| Serie and Range | Tolerance | ROHS         | Packing        |
|-----------------|-----------|--------------|----------------|
| S12008-680      | K         | R            | TR             |
|                 | J = 5%    | R = ROHS     | BU = Bulk Ware |
|                 | K = 10%   | N = non ROHS | TR = Tape Reel |
|                 | M = 20%   |              |                |
|                 | N = 30%   |              |                |

### Soldering Profile for Lead Free Soldering 235-240°C



### Soldering Profile for Lead Free Soldering 255-260°C



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